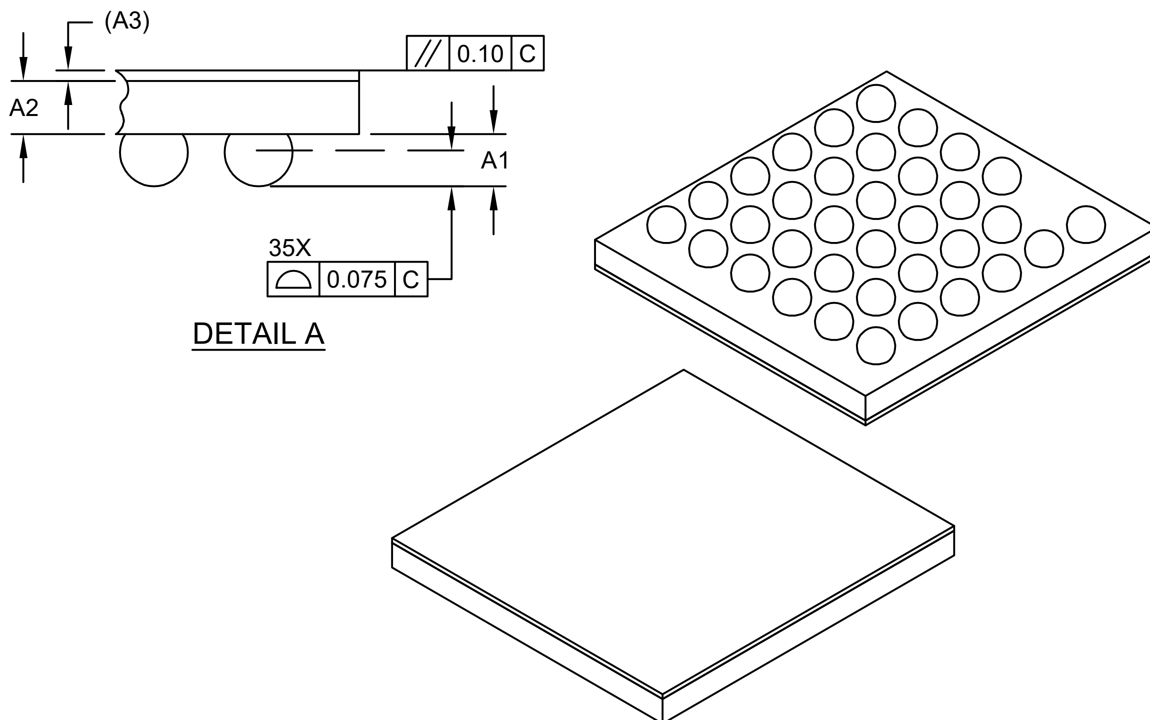
35-Ball Wafer Level Chip Scale Package (GFB) - 2.78x2.578x0.443 mm Body [WCLSP]
Atmel Global Package Code GJS

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	35		
Pitch	e	0.40 BSC		
Overall Height	A	0.403	0.443	0.483
Bump Height	A1	0.17	–	0.23
Die Thickness	A2	0.178	0.203	0.228
Backside Coating	A3	0.04 REF		
Overall Length	D	2.578 BSC		
Overall Bump Pitch	D1	2.00 BSC		
Overall Width	E	2.78 BSC		
Overall Bump Pitch	E1	2.00 BSC		
Bump Diameter	b	0.23	0.26	0.29

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.